

Please amend the claims as indicated below:

1. (Cancelled)

2. (Currently amended) A mold according to claim [[1]] 10, wherein the contact ~~section~~ member of the mold which is adapted to engage with the surface of the semiconductor chip, is in the form of a removable member which is mounted on one of the mold halves.

3. (Original) A mold according to claim 2, wherein the removable member is mounted for movement relative to the mold half on which it is mounted.

4. (Currently amended) A mold according to claim 3, further comprising ~~biasing means~~ an element operative to bias the removable member into the mold cavity defined by the mold halves.

5-6. (Cancelled)

7. (Withdrawn) A method of molding material around a semiconductor chip, the method comprising mounting a semiconductor chip on a substrate, inserting the substrate and the semiconductor chip into a mold, such that a contact section of the mold contacts a surface of the chip, molding the molding material around the semiconductor chip and the contact section to form a molded package, and subsequently removing the molded package from the mold.

8. (Withdrawn) A method according to claim 7, wherein the surface of the chip contacted by the contact section is an active surface of the chip.

9. (Withdrawn) A method according to claim 7, wherein the surface of the chip contacted by the contact section is a non-active surface of the chip.

10. (New) A mold comprising:
two mold halves,
the mold including portions configured to define the shape of a cavity which receives molding material for encapsulating a semiconductor chip;
one of the mold halves including an aperture extending therethrough and
a contact member formed of a compressible material, and positioned in the aperture,
the contact member being so shaped and positioned that it is in contact with a surface of a semiconductor chip being encapsulated in the mold.

11. (New) A mold comprising:
two mold halves,
the mold including portions configured to define the shape of a cavity which receives molding material for encapsulating a semiconductor chip;
one of the mold halves including an aperture extending therethrough and
a contact member positioned in the aperture,
the contact member being so shaped and positioned that a portion thereof is in contact with a portion of the surface of a semiconductor chip being encapsulated in the mold, and wherein
the portion of the contact member which is in contact with the portion of the surface of the semiconductor chip is so profiled as to minimize seepage of molding material onto the portion of the surface of the semiconductor chip during molding.